

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.49	100.0	7.7
			Subtotal	0.49	100	7.7
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01	0.04	0.23
	Copper alloy	Iron (Fe)	7439-89-6	0.04	0.1	0.58
	Copper alloy	Copper (Cu)	7440-50-8	36.84	99.86	584.18
			Subtotal	36.89	100	584.99
Mould Compound	Polymer	Tetrabromobisphenol A/Epichlorohydrin polymer	40039-93-8	1.84	3.0	29.13
	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	3.67	6.0	58.26
	Polymer	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	6.12	10.0	97.1
	Carbon Black	Carbon black	1333-86-4	0.31	0.5	4.86
	Filler	Misc. Silica compounds (generic)	14808-60-7	47.76	78.0	757.38
	Flame retardant	Antimony Trioxide (Sb2O3) - cas no. 1309-64-4	1309-64-4	1.53	2.5	24.27
			Subtotal	61.23	100	971
Post-plating	Pure Metal	Tin (Sn)	7440-31-5	0.63	100.0	10
			Subtotal	0.63	100	10
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.02	100.0	0.26
	Pure metal	Aluminium (Al)	7429-90-5	0.29	100.0	4.62
			Subtotal	0.31	200	4.88
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.02	5.0	0.36
	Lead alloy	Silver (Ag)	7440-22-4	0.01	2.5	0.18
	Lead alloy	Lead (Pb)	7439-92-1	0.42	92.5	6.62
			Subtotal	0.45	100	7.16
			Total	100	100	1585.73

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